



In the United States Patent and Trademark Office

Serial Number: 10/728,929  
Application. Filed: December 8, 2003  
Applicant: Kia Silverbrook  
Application. Title: Chips with wafer scale caps formed by molding  
Examiner/GAU: James M. Mitchell

Dated August 10, 2005  
At: Balmain, NSW  
Docket No. ZG112US

**AMENDMENT A**

Commissioner for Patents  
Washington, District of Columbia 20231

Dear Sir:

This paper is submitted in response to the Office Action mailed June 28, 2005 in relation to the above referenced application. The Applicant respectfully requests entrance of the following Amendment into the case and consideration of the following remarks.

**Amendments to the Specification** begin on page 2 of this paper. The Applicant submits that these amendments introduce no new matter.

**Amendments to the Claims** begin on page 3 of this paper. The Applicant submits that these amendments introduce no new matter.

**Remarks/Arguments** begin on page 6 of this paper.